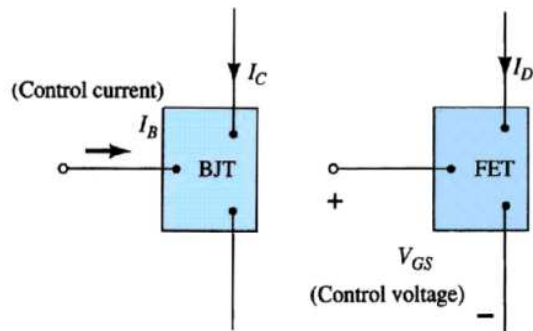


Introduction to FET's

Current Controlled vs Voltage Controlled Devices



3

Types of FET's

- JFET – Junction Field Effect Transistor
- MOSFET – Metal Oxide Semiconductor Field Effect Transistor
 - D-MOSFET - Depletion Mode MOSFET
 - E- MOSFET - Enhancement Mode MOSFET

4

Transfer Characteristics

The input-output transfer characteristic of the JFET is not as straight forward as it is for the BJT

In a BJT, β (h_{FE}) defined the relationship between I_B (input current) and I_C (output current).

In a JFET, the relationship (Shockley's Equation) between V_{GS} (input voltage) and I_D (output current) is used to define the transfer characteristics, and a little more complicated (and not linear):

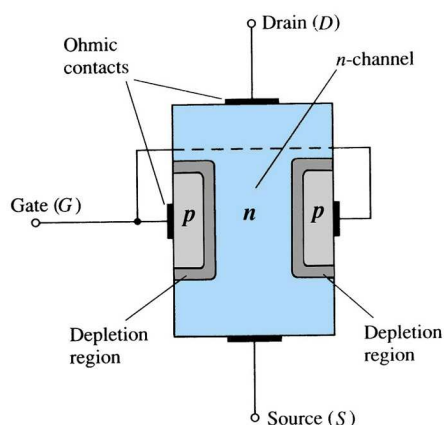
$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

As a result, FET's are often referred to a square law devices

5

JFET Construction

There are two types of JFET's: n-channel and p-channel.
The n-channel is more widely used.



There are three terminals: Drain (D) and Source (S) are connected to n-channel
Gate (G) is connected to the p-type material

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JFET Operating Characteristics

There are three basic operating conditions for a JFET:

JFET's operate in the depletion mode only

- A. $V_{GS} = 0$, V_{DS} is a minimum value depending on I_{DSS} and the drain and source resistance
- B. $V_{GS} < 0$, V_{DS} at some positive value and
- C. Device is operating as a Voltage-Controlled Resistor

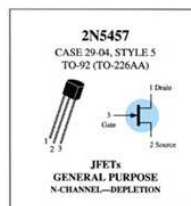
For an n channel JFET, V_{GS} may never be positive*

For an p channel JFET, V_{GS} may never be negative*

7

Specification Sheet (JFETs)

MAXIMUM RATINGS			
Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	25	Vdc
Drain-Gate Voltage	V_{DG}	25	Vdc
Reverse Gate-Source Voltage	V_{GSS}	-25	Vdc
Gate Current	I_G	10	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	310	mW
Junction Temperature Range	T_J	125	$^\circ\text{C}$
Storage Channel Temperature Range	T_{stg}	-65 to +150	$^\circ\text{C}$



ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Gate-Source Breakdown Voltage ($I_G = -10 \mu\text{A}$, $V_{DS} = 0$)	$V_{GS(off)}$	-25	-	-	Vdc
Gate Reverse Current ($V_{GS} = -15 \text{ Vdc}$, $V_{DS} = 0$) ($V_{GS} = -15 \text{ Vdc}$, $V_{DS} = 0$, $T_A = 100^\circ\text{C}$)	I_{GRS}	-	-	-1.0 -200	nA μA
Gate Source Cutoff Voltage ($V_{DS} = 15 \text{ Vdc}$, $I_D = 10 \text{ mA}$)	$V_{GS(off)}$	-2N5457	-0.5	-6.0	Vdc
Gate Source Voltage ($V_{DS} = 15 \text{ Vdc}$, $I_D = 100 \mu\text{A}$)	V_{GS}	-	-2.5	-	Vdc

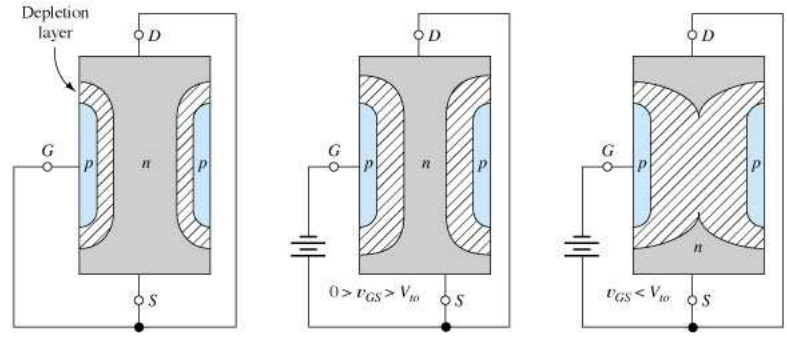
ON CHARACTERISTICS						
Zero-Gate-Voltage Drain Current* ($V_{GS} = 15 \text{ Vdc}$, $V_{DS} = 0$)	I_{DSS}	2N5457	1.0	3.0	5.0	mA

SMALL-SIGNAL CHARACTERISTICS						
Forward Transfer Admittance Common Source* ($V_{GS} = 15 \text{ Vdc}$, $V_{DS} = 0$, $f = 1.0 \text{ kHz}$)	Y_{fs}	2N5457	1000	-	5000	μmhos
Output Admittance Common Source* ($V_{GS} = 15 \text{ Vdc}$, $V_{DS} = 0$, $f = 1.0 \text{ kHz}$)	Y_{os}	-	-	10	50	μmhos
Input Capacitance ($V_{GS} = 15 \text{ Vdc}$, $V_{DS} = 0$, $f = 1.0 \text{ MHz}$)	C_{iss}	-	4.5	7.0	-	pF
Reverse Transfer Capacitance ($V_{GS} = 15 \text{ Vdc}$, $V_{DS} = 0$, $f = 1.0 \text{ MHz}$)	C_{rss}	-	1.5	3.0	-	pF

*Pulse Test: Pulse Width ≤ 100 ns; Duty Cycle ≤ 10%

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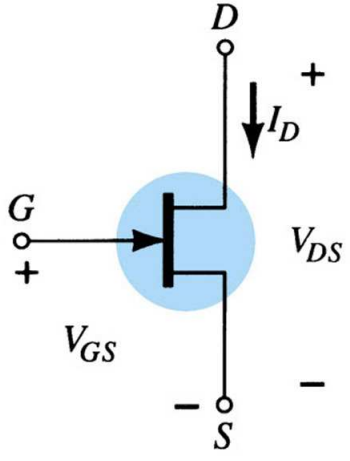
N-Channel JFET Operation



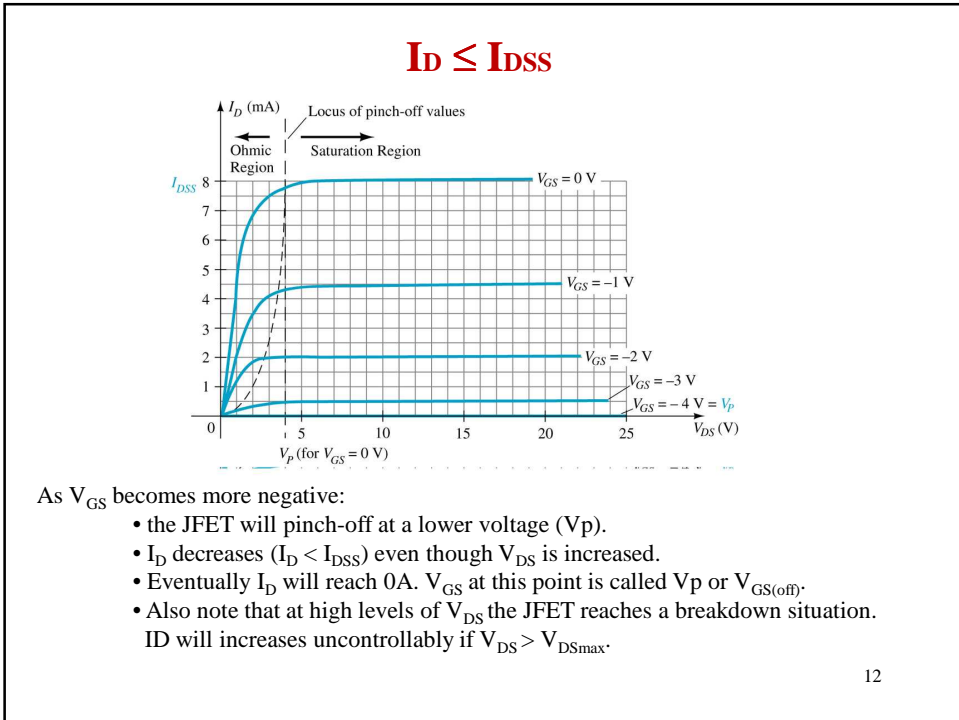
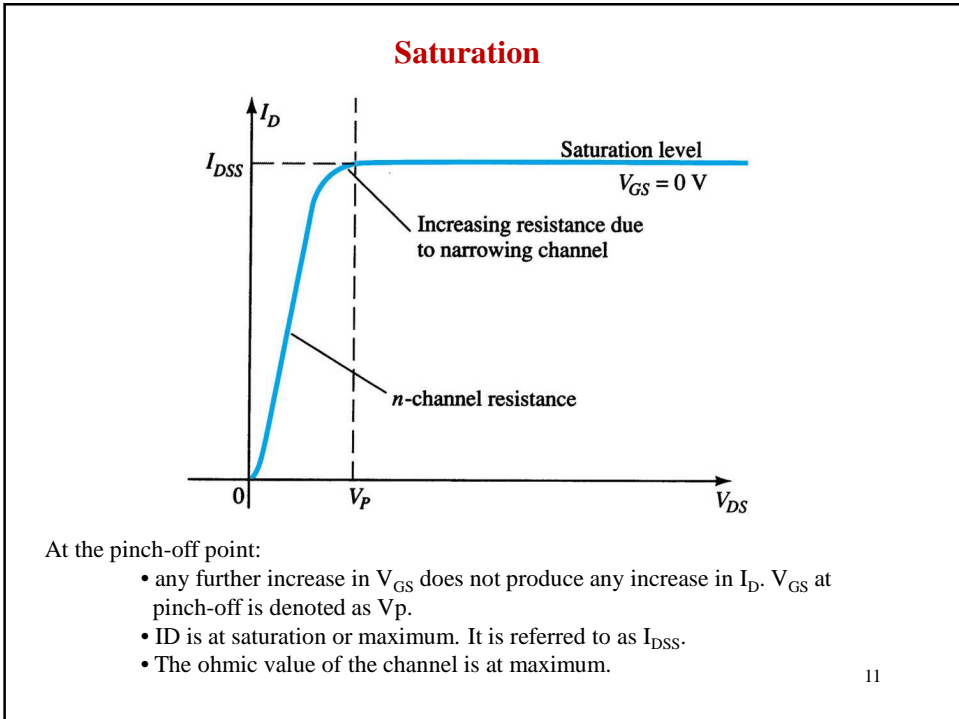
(a) Bias is zero and depletion layer is thin; low-resistance channel exists between the drain and the source
 (b) Moderate gate-to-channel reverse bias results in narrower channel
 (c) Bias greater than pinch-off voltage; no conductive path from drain to source

The nonconductive depletion region becomes thicker with increased reverse bias.
 (Note: The two gate regions of each FET are connected to each other.)

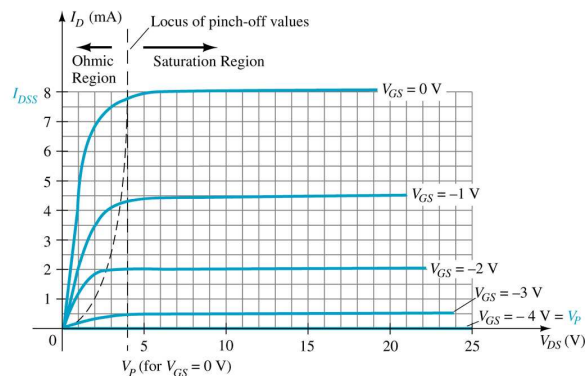
N-Channel JFET Symbol



(a)



FET as a Voltage-Controlled Resistor



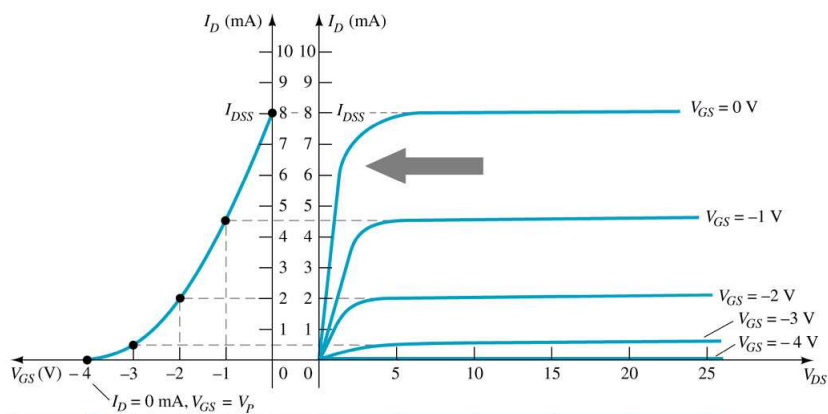
The region to the left of the pinch-off point is called the *ohmic region*.

The JFET can be used as a variable resistor, where V_{GS} controls the drain-source resistance (r_d). As V_{GS} becomes more negative, the resistance (r_d) increases.

$$r_d = \frac{r_o}{\left(1 - \frac{V_{GS}}{V_P}\right)^2}$$

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Transfer (Transconductance) Curve



From this graph it is easy to determine the value of I_D for a given value of V_{GS} . It is also possible to determine I_{DSS} and V_P by looking at the knee where V_{GS} is 0.

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Plotting the Transconductance Curve

Using I_{DSS} and V_P (or $V_{GS(off)}$) values found in a specification sheet, the Family of Curves can be plotted by making a table of data using the following 3 steps:

Step 1:

$$\text{Solve } I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2 \quad \text{for } V_{GS} = 0V$$

Step 2

$$\text{Solve } I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2 \quad \text{for } V_{GS} = V_P \text{ (aka } V_{GS(off)} \text{)}$$

Step 3:

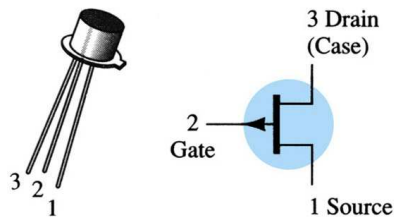
$$\text{Solve } I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2 \quad \text{for } 0V \geq V_{GS} \geq V_P \text{ in } 1V \text{ increments for } V_{GS}$$

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Case Construction and Terminal Identification

2N2844

CASE 22-03, STYLE 12
TO-18 (TO-206AA)



JFETs
GENERAL PURPOSE
P-CHANNEL

This information is found on the specification sheet

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p-Channel JFET's

p-Channel JFET operates in a similar manner as the n-channel JFET except the voltage polarities and current directions are reversed

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P-Channel JFET Characteristics

As V_{GS} increases more positively

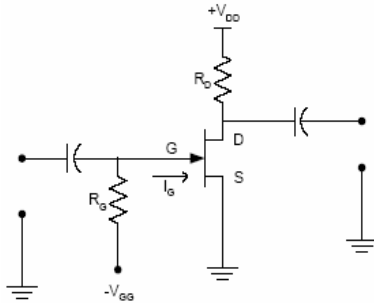
- the depletion zone increases
- I_D decreases ($I_D < I_{DSS}$)
- eventually $I_D = 0A$

Also note that at high levels of V_{DS} the JFET reaches a breakdown situation. I_D increases uncontrollably if $V_{DS} > V_{DSmax}$.

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JFET Biasing Circuits Count...

Gate Bias: or Fixed Bias Ckt.



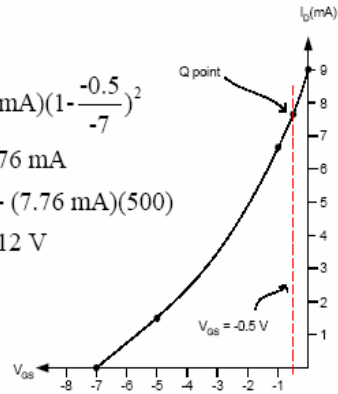
Since $I_G = 0$, $V_{GS} = V_{GG}$
 $V_{DS} = V_{DD} - I_D R_D$

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_{GS(off)}}\right)^2$$

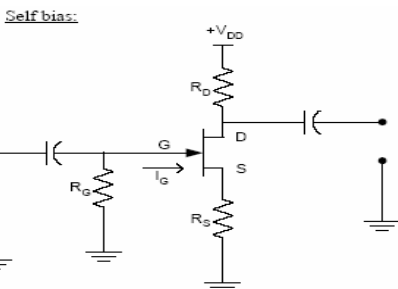
- Example:** Determine the Q-point values for the gate biasing circuit if $V_{GG} = -0.5\text{ V}$, $V_{GS(off)} = -7\text{ V}$, $I_{DSS} = 9\text{ mA}$, $V_{DD} = 5\text{ V}$ and $R_D = 500\Omega$.

$$I_D = (9\text{mA}) \left(1 - \frac{-0.5}{-7}\right)^2 = 7.76\text{ mA}$$

$$V_{DS} = 5 - (7.76\text{ mA})(500) = 1.12\text{ V}$$



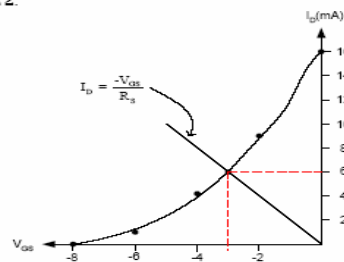
JFET Self (or Source) Bias Circuit



Since $I_G = 0$, $V_G = 0$
 $V_S = I_D R_S$ $I_D = \frac{-V_{GS}}{R_S}$
 $V_{GS} = -I_D R_S$
 $V_{DS} = V_{DD} - I_D (R_D + R_S)$
 and
$$I_{DS} = I_{DSS} \left(1 - \frac{V_{GS}}{V_P}\right)^2$$

$$\therefore I_{DSS} \left(1 - \frac{V_{GS}}{V_P}\right)^2 = -\frac{V_{GS}}{R_S}$$

- Example:** Determine the Q-point values for the self biasing circuit if $V_{GS(off)} = -8\text{ V}$, $I_{DSS} = 16\text{ mA}$, $V_{DD} = 10\text{ V}$, $R_D = 500\Omega$, $R_G = 1\text{ M}\Omega$ and $R_S = 500\Omega$.



$$I_D = 6\text{ mA}$$

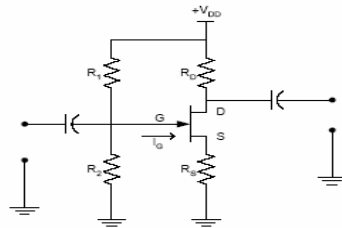
$$V_{DS} = 10 - (6\text{mA})(500+500) = 4\text{ V}$$

$$I_{DSS} \left[1 - 2 \frac{V_{GS}}{V_P} + \left(\frac{V_{GS}}{V_P}\right)^2 \right] + \frac{V_{GS}}{R_S} = 0$$

This quadratic equation can be solved for V_{GS} & I_{DS}

The Potential (Voltage) Divider Bias

Voltage-divider bias:



Since $I_G = 0$,

$$V_G = \frac{R_2}{R_1 + R_2} V_{DD}$$

$$I_D = \frac{V_S}{R_S} = \frac{V_G - V_{GS}}{R_S}$$

$$\therefore I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2 - \frac{V_G - V_{GS}}{R_S} = 0$$

Solving this quadratic equation gives V_{GS} and I_{DS}

The method used to plot the dc bias line for the voltage-divider bias is as follows:

1. Plot the transconductance curve for the specific JFET.
2. Calculate V_G .
3. Plot V_G on the positive x-axis.

4. Solve for I_D using

$$I_D = \frac{V_G}{R_S}$$

5. Plot I_D found in (4) on the y-axis.

6. Extend the line to intersect the transconductance curve to obtain the Q-point values.

MOSFET's

MOSFETs

MOSFETs have characteristics similar to JFETs and additional characteristics that make them very useful

There are 2 types of MOSFET's:

- Depletion mode MOSFET (D-MOSFET)
 - Operates in Depletion mode the same way as a JFET when $V_{GS} \leq 0$
 - Operates in Enhancement mode like E-MOSFET when $V_{GS} > 0$
- Enhancement Mode MOSFET (E-MOSFET)
 - Operates in Enhancement mode
 - $I_{DSS} = 0$ until $V_{GS} > V_T$ (threshold voltage)

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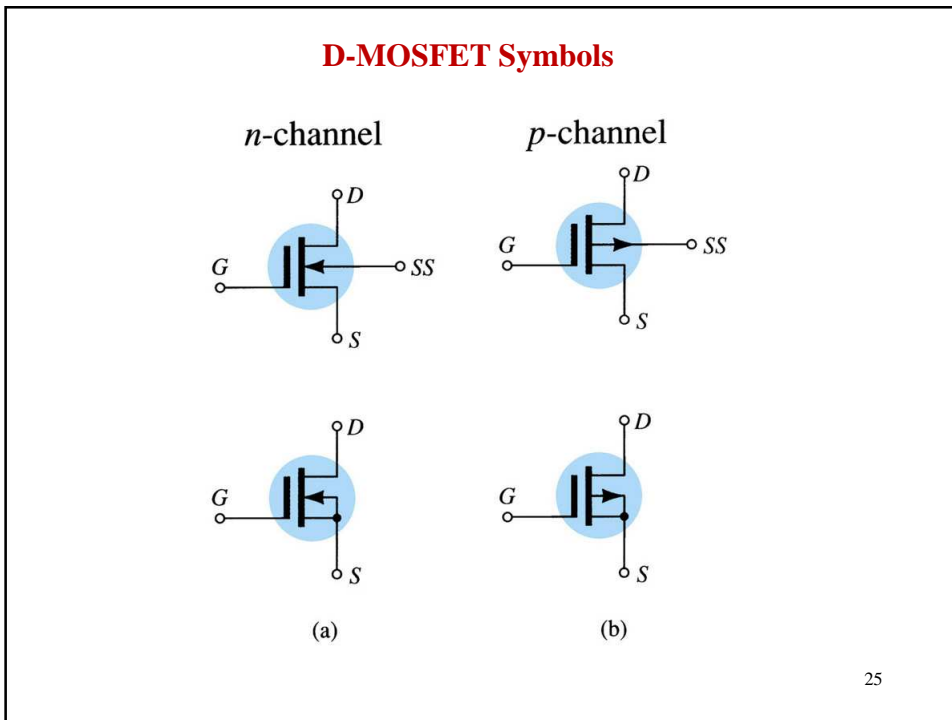
MOSFET Handling

MOSFETs are very static sensitive. Because of the very thin SiO_2 layer between the external terminals and the layers of the device, any small electrical discharge can establish an unwanted conduction.

Protection:

- Always transport in a static sensitive bag
- Always wear a static strap when handling MOSFETS
- Apply voltage limiting devices between the Gate and Source, such as back-to-back Zeners to limit any transient voltage

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Specification Sheet

2N3797
CASE 22-03, STYLE 2
TO-18 (FO-266AA)

MOSFET
LOW POWER AUDIO
N-CHANNEL - DEPLETION

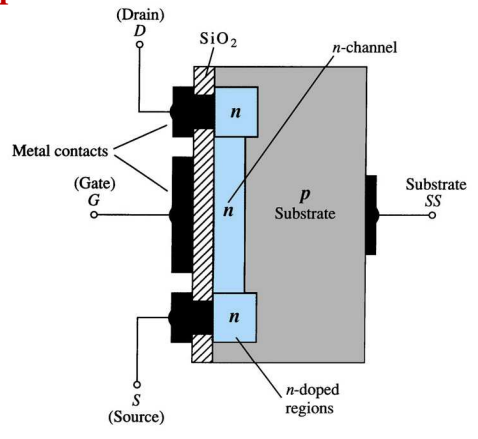
MAXIMUM RATINGS			
Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	Vdc
Gate-Source Voltage	V_{GS}	+10	Vdc
Drain Current	I_D	20	mA dc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Drain-Source 25°C	P_D	200	mW
Junction Temperature Range	T_J	+175	$^\circ\text{C}$
Storage Channel Temperature Range	T_{stg}	-65 to +200	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)					
Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Drain-Source Breakdown Voltage ($V_{GS} = -1.0\text{ V}$, $I_D = 5.0\ \mu\text{A}$)	$V_{DS(BR)}$	20	25	-	Vdc
Gate-Source Current (1) ($V_{DS} = -10\text{ V}$, $V_{GS} = 0$ $V_{GS} = -10\text{ V}$, $I_D = 0$, $T_A = 150^\circ\text{C}$)	I_{GS}	-	-	1.0	μA
Gate-Source Cutoff Voltage ($I_D = 2.0\ \mu\text{A}$, $V_{DS} = 10\text{ V}$)	$V_{GS(off)}$	-	-5.0	-7.0	Vdc
Drain-Gate Reverse Current (1) ($V_{DS} = 10\text{ V}$, $I_D = 0$)	I_{DGR}	-	-	1.0	μA
ON CHARACTERISTICS					
Zero-Gate Voltage Drain Current ($V_{GS} = 0\text{ V}$, $V_{DS} = 10\text{ V}$)	I_{DSS}	2.0	2.9	6.5	mA dc
On-State Drain Current ($V_{GS} = 10\text{ V}$, $V_{DS} = 3.5\text{ V}$)	$I_{D(on)}$	9.0	14	18	mA dc
SMALL-SIGNAL CHARACTERISTICS					
Forward Transfer Admittance ($V_{GS} = 10\text{ V}$, $V_{DS} = 0$, $f = 1.0\text{ kHz}$)	Y_{fs}	-	1900	2300	μmhos
($V_{GS} = 10\text{ V}$, $V_{DS} = 0$, $f = 1.0\text{ MHz}$)	Y_{fs}	-	1300	-	μmhos
Output Admittance ($V_{GS} = 10\text{ V}$, $V_{DS} = 0$, $f = 1.0\text{ kHz}$)	Y_{os}	-	27	60	μmhos
Input Capacitance ($V_{GS} = 10\text{ V}$, $V_{DS} = 0$, $f = 1.0\text{ MHz}$)	C_{iss}	-	6.0	8.0	μF
Reverse Transfer Capacitance ($V_{GS} = 10\text{ V}$, $V_{DS} = 15\text{ V}$, $f = 1.0\text{ MHz}$)	C_{rfs}	-	0.5	0.8	μF
FUNCTIONAL CHARACTERISTICS					
Noise Figure ($V_{GS} = 10\text{ V}$, $V_{DS} = 0$, $f = 1.0\text{ kHz}$, $R_G = 3\text{ megohms}$)	NF	-	3.8	-	dB

(1) This value of current includes both the FET leakage current as well as the leakage current associated with the test socket and fixture when measured under test circuit conditions.

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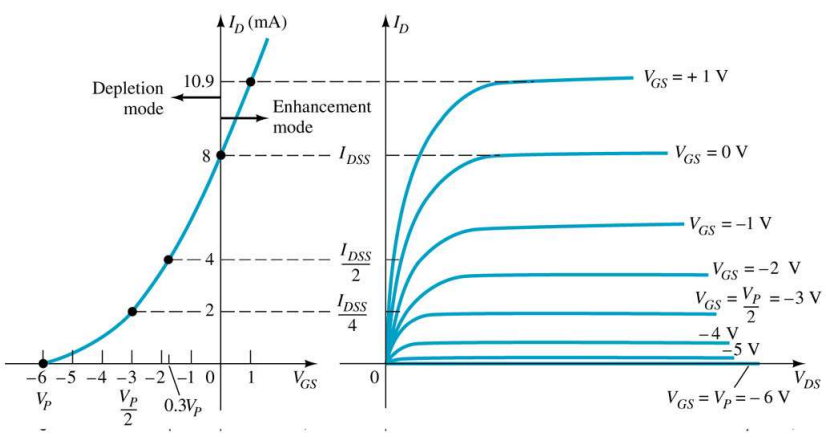
Depletion Mode MOSFET Construction



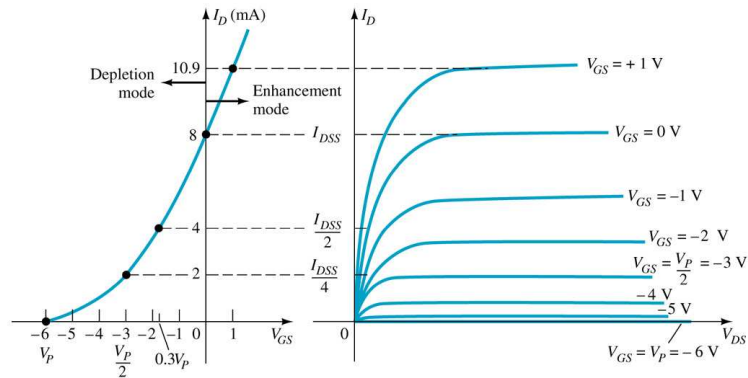
The Drain (D) and Source (S) leads connect to the to n-doped regions
 These N-doped regions are connected via an n-channel
 This n-channel is connected to the Gate (G) via a thin insulating layer of SiO₂
 The n-doped material lies on a p-doped substrate that may have an additional terminal connection called SS

Basic Operation

A D-MOSFET may be biased to operate in two modes:
 the **Depletion** mode or the **Enhancement** mode



D-MOSFET Depletion Mode Operation



The transfer characteristics are similar to the JFET

In Depletion Mode operation:

When $V_{GS} = 0V$, $I_D = I_{DSS}$

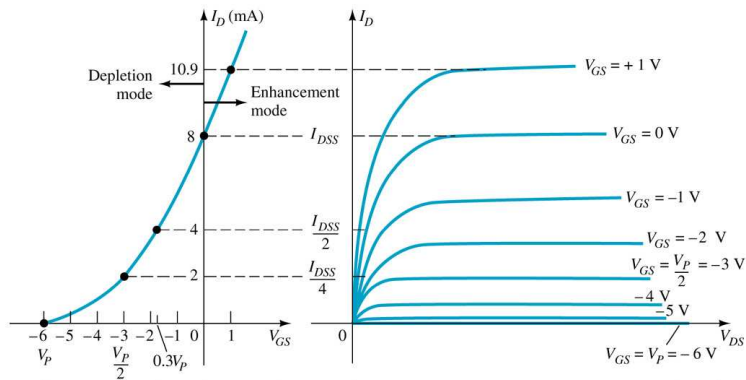
When $V_{GS} < 0V$, $I_D < I_{DSS}$

When $V_{GS} > 0V$, $I_D > I_{DSS}$

The formula used to plot the Transfer Curve, is: $I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$

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D-MOSFET Enhancement Mode Operation



Enhancement Mode operation

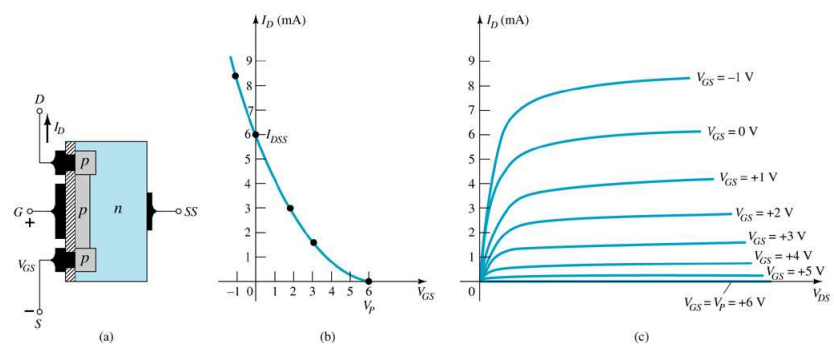
In this mode, the transistor operates with $V_{GS} > 0V$, and I_D increases above I_{DSS}

Shockley's equation, the formula used to plot the Transfer Curve, still applies but V_{GS} is positive:

$$I_D = I_{DSS} \left(1 + \frac{V_{GS}}{V_P} \right)^2$$

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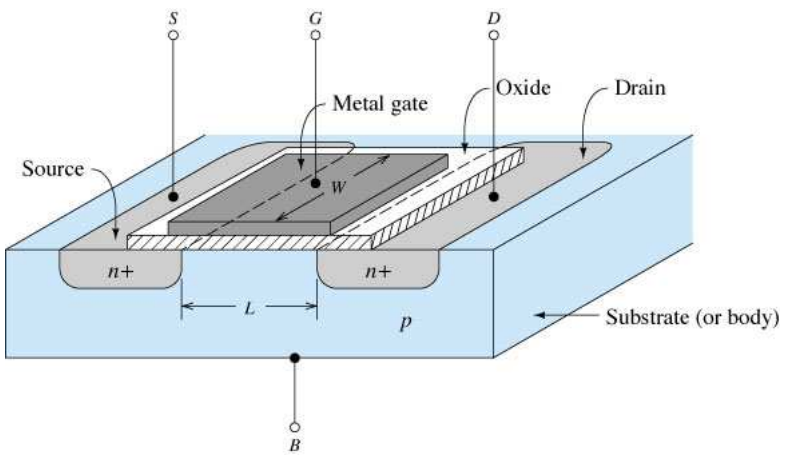
p-Channel Depletion Mode MOSFET



The p-channel Depletion mode MOSFET is similar to the n-channel except that the voltage polarities and current directions are reversed

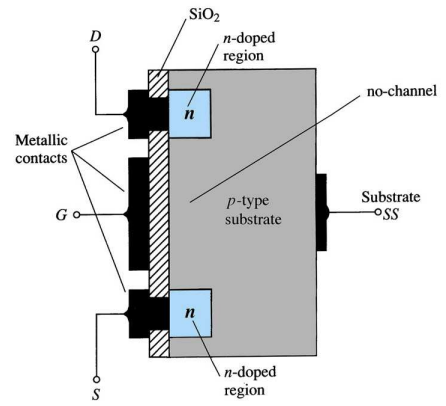
Enhancement Mode MOSFET's

n*-Channel E-MOSFET showing channel length *L* and channel width *W



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Enhancement Mode MOSFET Construction



The Drain (D) and Source (S) connect to the n-doped regions
 These n-doped regions are not connected via an n-channel without an external voltage
 The Gate (G) connects to the p-doped substrate via a thin insulating layer of SiO₂
 The n-doped material lies on a p-doped substrate that may have an additional terminal connection called SS

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Specification Sheet

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	25	Vdc
Drain-Gate Voltage	V_{DG}	30	Vdc
Gate-Source Voltage*	V_{GS}	30	Vdc
Drain Current	I_{DQ}	30	mAdc
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Below above 25°C	P_D	800	mW
Junction Temperature Range	T_j	-55 to +175	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-65 to +175	$^\circ\text{C}$

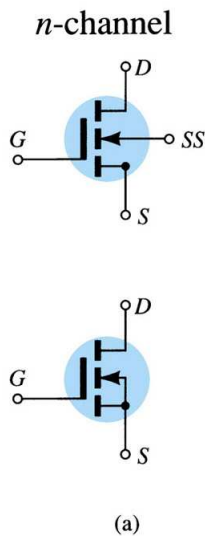


* Maximum junction temperature is 175 $^\circ\text{C}$ unless otherwise noted.

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Drain-Source Breakdown Voltage ($I_D = 10 \mu\text{A}, V_{GS} = 0$)	$V_{DS(BR)}$	25	-	Vdc
Zero-Gate-Voltage Drain Current ($V_{GS} = 0\text{V}, V_{DS} = 0$) $T_A = 25^\circ\text{C}$	I_{DSS}	-	10	μA
($T_A = 150^\circ\text{C}$)		-	10	μA
Gate Reverse Current ($V_{GS} = \pm 15\text{Vdc}, V_{DS} = 0$)	I_{GR}	-	8	μA
ON CHARACTERISTICS				
Gate Threshold Voltage ($V_{GS} = 10\text{V}, I_D = 10\text{mA}$)	$V_{GS(th)}$	1.0	5	Vdc
Drain-Source On Voltage ($I_D = 2.0\text{mA}, V_{GS} = 10\text{V}$)	$V_{DS(on)}$	-	1.6	V
On-State Drain Current ($V_{GS} = 10\text{V}, V_{DS} = 10\text{V}$)	$I_{D(on)}$	3.0	-	mAdc
SMALL-SIGNAL CHARACTERISTICS				
Forward Transfer Admittance ($V_{GS} = 10\text{V}, I_D = 2.0\text{mA}, f = 1.0\text{kHz}$)	$ Y_{fs} $	1000	-	μmho
Input Capacitance ($V_{GS} = 10\text{V}, V_{DS} = 0, f = 140\text{kHz}$)	C_{iss}	-	5.0	pF
Reverse Transfer Capacitance ($V_{GS} = 0, V_{DS} = 5\text{V}, f = 140\text{kHz}$)	C_{rss}	-	1.3	pF
Drain-Source Capacitance ($V_{GS} = 10\text{V}, f = 140\text{kHz}$)	C_{oss}	-	5.0	pF
Drain-Source Resistance ($V_{GS} = 10\text{V}, I_D = 10\text{mA}, f = 1.0\text{kHz}$)	$r_{DS(on)}$	-	300	Ω
SWITCHING CHARACTERISTICS				
Turn-On Delay (Fig. 5)	$t_{D(on)}$	-	45	ns
Rise Time (Fig. 6)	t_r	-	65	ns
Turn-Off Delay (Fig. 7)	$t_{D(off)}$	-	60	ns
Fall Time (Fig. 8)	t_f	-	100	ns

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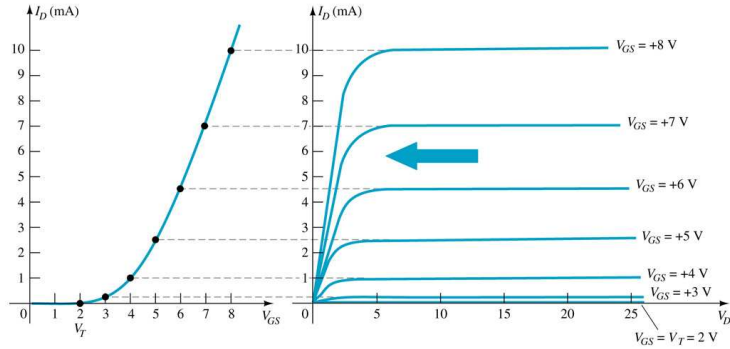
E-MOSFET Symbols



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Basic Operation

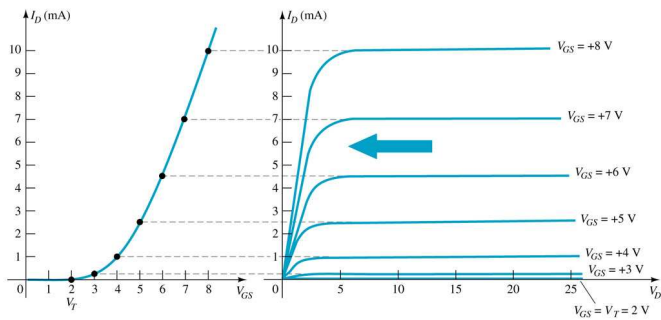
The Enhancement mode MOSFET only operates in the enhancement mode.



- V_{GS} is always positive
- I_{DSS} = 0 when V_{GS} < V_T
- As V_{GS} increases above V_T, I_D increases
- If V_{GS} is kept constant and V_{DS} is increased, then I_D saturates (I_{DSS})
- The saturation level, V_{DSsat} is reached.

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Transfer Curve



To determine I_D given V_{GS}: $I_D = k (V_{GS} - V_T)^2$ $k = \frac{I_{D(on)}}{(V_{GS(on)} - V_T)^2}$
 where V_T = threshold voltage or voltage at which the MOSFET turns on.

k = constant found in the specification sheet

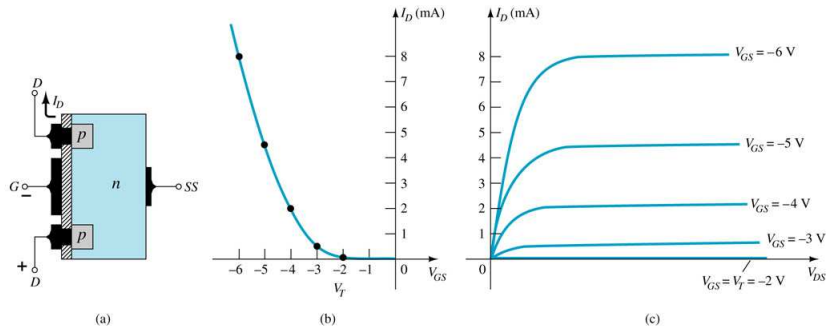
The PSpice determination of k is based on the geometry of the device:

$$k = \left(\frac{W}{L}\right) \left(\frac{KP}{2}\right) \quad \text{where } KP = \mu_n C_{ox}$$

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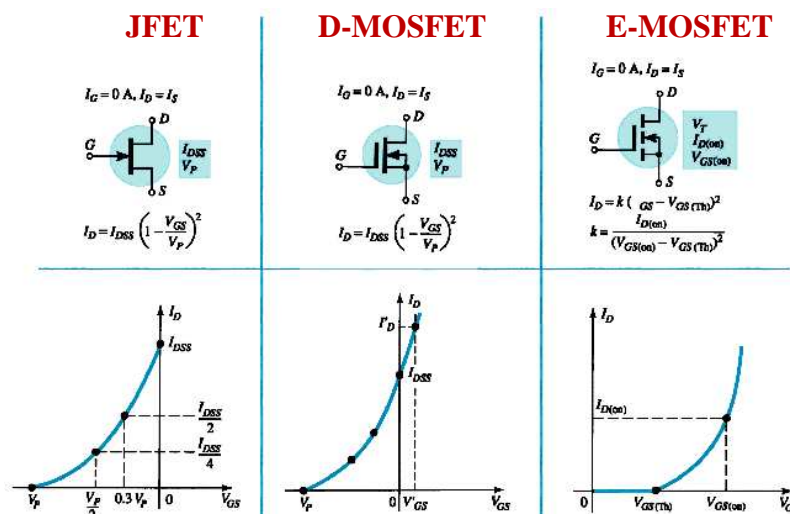
p-Channel Enhancement Mode MOSFETs

The p-channel Enhancement mode MOSFET is similar to the n-channel except that the voltage polarities and current directions are reversed.



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Summary Table



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